

L Number	Hits	Search Text	DB	Time stamp
-	1081225	substrate or chip or lot or wafer or semiconductor	USPAT; US-PGPUB; IBM_TDB	2004/08/20 15:17
-	31499	((substrate or chip or lot or wafer or semiconductor) and (defect\$1 same substrate))	USPAT; US-PGPUB; IBM_TDB	2004/08/11 14:04
-	488	((substrate or chip or lot or wafer or semiconductor) and (defect\$1 same substrate)) and (optical near1 inspect\$3)	USPAT; US-PGPUB; IBM_TDB	2004/08/11 14:04
-	160	((substrate or chip or lot or wafer or semiconductor) and (defect\$1 same substrate)) and (optical near1 inspect\$3) and (defect\$1 near1 locat\$4)	USPAT; US-PGPUB; IBM_TDB	2004/08/11 14:05
-	65	((substrate or chip or lot or wafer or semiconductor) and (defect\$1 same substrate)) and (optical near1 inspect\$3) and (defect\$1 near1 locat\$4) and (cluster\$1 or signature\$1)	USPAT; US-PGPUB; IBM_TDB	2004/08/11 14:31
-	0	defect\$1 adj by adj location	USPAT; US-PGPUB; IBM_TDB	2004/08/11 14:31
-	1179	defect\$1 adj1 location	USPAT; US-PGPUB; IBM_TDB	2004/08/11 14:32
-	23	((substrate or chip or lot or wafer or semiconductor) and (defect\$1 same substrate)) and (optical near1 inspect\$3) and (defect\$1 near1 locat\$4) and (cluster\$1 or signature\$1) and ((substrate or chip or lot or wafer or semiconductor) and (defect\$1 same substrate)) and (defect\$1 adj1 location)	USPAT; US-PGPUB; IBM_TDB	2004/08/12 19:09
-	227	((substrate or chip or lot or wafer or semiconductor) and (defect\$1 same substrate)) and (defect\$1 adj1 location)	USPAT; US-PGPUB; IBM_TDB	2004/08/20 15:59
-	227	((substrate or chip or lot or wafer or semiconductor) and (defect\$1 same substrate)) and (defect\$1 adj1 location)	USPAT; US-PGPUB; IBM_TDB	2004/08/16 15:35
-	16749	(bound\$3 near1 (box or area))	USPAT; US-PGPUB; IBM_TDB	2004/08/16 15:39
-	8	((substrate or chip or lot or wafer or semiconductor) and (defect\$1 same substrate)) and (defect\$1 adj1 location) and ((bound\$3 near1 (box or area)))	USPAT; US-PGPUB; IBM_TDB	2004/08/16 15:36
-	3389	bound\$3 near1 box	USPAT; US-PGPUB; IBM_TDB	2004/08/20 15:59
-	36827	(inspect\$3 or detect\$3) same defect\$1	USPAT; US-PGPUB; IBM_TDB	2004/08/16 15:40
-	175	(bound\$3 near1 box) and ((inspect\$3 or detect\$3) same defect\$1)	USPAT; US-PGPUB; IBM_TDB	2004/08/20 15:44
-	112407	signature\$1 or cluster	USPAT; US-PGPUB; IBM_TDB	2004/08/16 15:40
-	78	((bound\$3 near1 box) and ((inspect\$3 or detect\$3) same defect\$1)) and (signature\$1 or cluster)	USPAT; US-PGPUB; IBM_TDB	2004/08/16 15:41
-	156	reticle and mask and monolithic	USPAT; US-PGPUB; IBM_TDB	2004/08/20 15:27
-	4	(reticle and mask and monolithic) and (optical near1 inspection)	USPAT; US-PGPUB; IBM_TDB	2004/08/20 15:28
-	3395	bound\$3 near1 box	USPAT; US-PGPUB; IBM_TDB	2004/08/20 15:59

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-	1334	((bound\$3 near1 box) and overlap	USPAT; US-PGPUB; IBM_TDB	2004/08/20 15:59
-	228	((substrate or chip or lot or wafer or semiconductor) and (defect\$1 same substrate)) and (defect\$1 adj1 location)	USPAT; US-PGPUB; IBM_TDB	2004/08/20 16:00
-	0	((bound\$3 near1 box) and overlap) and (((substrate or chip or lot or wafer or semiconductor) and (defect\$1 same substrate)) and (defect\$1 adj1 location))	USPAT; US-PGPUB; IBM_TDB	2004/08/20 15:59
-	635	((bound\$3 near1 box) and overlap) and (substrate or chip or lot or wafer or semiconductor)	USPAT; US-PGPUB; IBM_TDB	2004/08/20 16:00
-	95	((bound\$3 near1 box) and overlap) and (substrate or chip or lot or wafer or semiconductor) ) and defect	USPAT; US-PGPUB; IBM_TDB	2004/08/20 16:12
-	6	(correlat\$3 near1 defect\$1) and (position near1 stage)	USPAT; US-PGPUB; IBM_TDB	2004/08/21 13:13

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